ICEP-HBS 2026

ICEP 2026

2026 International Conference on Electronics Packaging and Hybrid Bonding Symposium

厳文 FP70159号

Date: April 14 - 18, 2026 "On-site Only"
Venue: International Conference Center Hiroshima, Japan
ICEP Sponsor: The Japan Institute of Electronics Packaging (JIEP)
ICEP Technical Co-Sponsors: IEEE EPS, IEEE EPS Japan Chapter, iMAPS, SMTA

Major Topics

Advanced Packaging

2.xD/3D, TSV/TGV   Substrates/interposers/RDL   Fan-out/in packaging   Wafer/panel level packaging   Automotive and IoT applications   High-performance computing   Heterogeneous integration technologies   Chiplet packaging   Hybrid bonding   Other related technologies

Design, Modeling, and Reliability

2.xD/3D, TSV/TGV, WLCSP, Fan-out/inAdvanced reliability evaluation (PDfR, etc.)   High-performance board design   Novel test methods and life models (LCA, TCAD, etc.)   Other related technologies

Emerging Technologies

Health/medical care and cosmetics devices   Stretchable/flexible electronics   Sensor and MEMS/NEMS/MOEMS packaging   Batteries and eco-friendly devices   Advanced MEMS/NEMS/MOEMS technologies   Packaging for quantum computing   Other related technologies

High-speed, Wireless & Components

3D-printed components   Antennas, RFs, and sensor modules   Highspeed applications (5G, LTE, etc.)   Automotive and IoT applications   Other related technologies

Interconnections

Interconnection methods (flip-chip, wire-bonding etc.)   2.xD/3D, TSV/TGV, fan-out/in interconnections   Embedded systems   Power electronics interconnections   Bio/medical and eco-friendly devices   Hybrid bonding   Other related technologies

Materials and Processes

Homo/heterogeneous bonding/assembly   Substrates, interposers and panels   Metallic materials & processes (plating, soldering, etc.)   Organic semiconductors (OLED, OFET, OPV, etc.)   Power electronic/battery materials & processes   Optoelectronic materials & processes   Additive manufacturing (compound, paste, 3D printing, etc.)   Die to Wafer, Wafer to Wafer, Debonding   Other related technologies

Power Electronics

Power device and module fabrication (HEMT, diode, IPM etc.)   Advanced Inverter & converter   Super capacitor   Harsh environment tolerant device & module   Si-based MOSFET, BJT, IGBT   Other related technologies

Thermal Management

Advanced cooling technologies   Thermal management structures (heat sinks, pipes, etc.)   Simulation, measurement, and evaluation methods   Other related technologies

Optoelectronics

3D/silicon photonics technologies   Optical connectors, waveguides, & transceivers   Device fabrication (LED, laser, sensor, etc.)   Mid/on-board module fabrication   Optical wafer/chip-scale packaging   Co-packaged optics   Other related technologies

Other Upcoming Technologies

New system concept & design   Any other topics related to ICEP scope

About ICEP

ICEP is the largest international conference on electronic packaging in Japan, attracting more than 900 attendees and hosting about 35 technical sessions. ICEP provides a strong platform to demonstrate your technologies and products as well as expand your customer network. It is jointly sponsored by JIEP, IEEE EPS, IEEE EPS Japan Chapter, iMAPS, and SMTA. The conference has technical sessions covering a wide range of topics including advanced packaging, design, modeling and reliability, emerging technologies, high-speed, wireless & components, interconnections, materials and processes, optoelectronics, power electronics integration, and thermal management. Since its inauguration in 2001, ICEP has developed into a highly reputed electronics packaging conference in Japan, attended by world-renowned experts in all aspects related to packaging technologies from all over the world.

Abstract and Paper Submission Deadline

Important dates
Abstract submission open: September 1, 2025
Abstract deadline: October 31, 2025
Notification of acceptance: December 15, 2025
Final manuscript deadline: January 30, 2026

- Please submit your abstract using the template available at the conference website. https://www.jiep.or.jp/icep/ You must include the novel, original, and unpublished contents and state the purposes, methods, results, and conclusions clearly in the abstract.
- Once an abstract has been accepted, a final 2-page paper in double-column format will be requested by the due date.
- Accepted papers will be submitted for inclusion into IEEE Xplore as well as other Abstracting and Indexing (A&I) databases (EI Compendex and INSPEC).
- The authors are required to release the copyright of all submitted contents in their final manuscripts. For details, visit: https://ux.nu/o27ui
- Authors of presented papers are strongly encouraged to submit their full paper (4-10 pages) to the Transactions of The Japan Institute of Electronics Packaging (a peer-reviewed international journal, https://www.jstage.jst.go.jp/browse/jiepeng/-char/en).
- IEEE reserves the right to exclude a paper from distribution after the conference, including IEEE Xplore® Digital Library, if the paper is not presented by the author at the conference.

Awards

The JIEP will award the Outstanding Technical Paper Award and the Poster Award to outstanding presentations and posters.
The IEEE EPS Japan Chapter will award the Young Award to outstanding young researchers.

Registration Fees

Member of JIEP: 65,000 JPY, Member of IEEE / IMAPS: 70,000 JPY, Non-Member: 80,000 JPY, Students: 20,000 JPY
Registration Fees include Reception and Proceedings.

Sponsorship Opportunities

We invite you to be a sponsor, which entitles your company to be exposed to the attendees in and outside the conference rooms. The sponsorship for ICEP-HBS 2026 ranges from 600,000 yen to 100,000 yen. As a sponsor, your company's name and logo will be published in the conference's official program and will appear on the ICEP website as well as various conference banners. Furthermore, a tabletop exhibition booth is available for the diamond, platinum, and gold sponsors to demonstrate and promote your products/services. Please contact the conference secretary for details.

Organizing Committee

General Chair: Yasuhiro Morikawa, ULVAC
General Vice Chairs: Toyohiro Aoki, IBM Japan
Ryo Endo, Rapidus
Takaaki Ishigure, Keio University

Contact

Secretariat of ICEP 2026 The Japan Institute of Electronics Packaging (JIEP)
E-mail: icep2026@jiep.or.jp
URL: https://www.jiep.or.jp/icep/

© TCVB